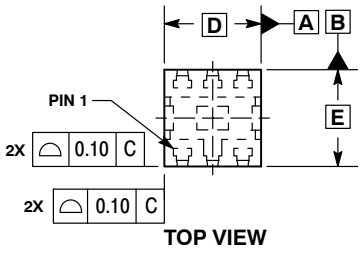
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

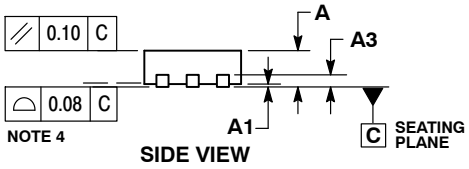
SCALE 2:1

CUDFN6 1.6x1.6, 0.5P
CASE 505AL
ISSUE A

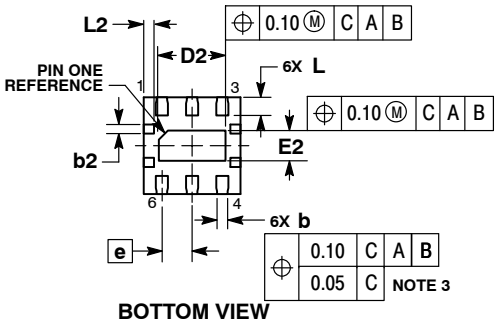
DATE 09 FEB 2017



TOP VIEW



SIDE VIEW



BOTTOM VIEW

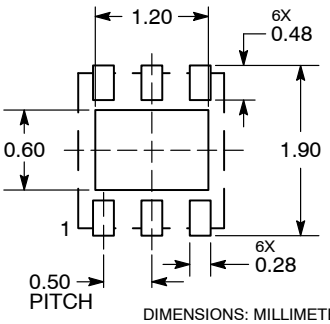
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.20MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.55	0.65
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
b2	0.15 REF	
D	1.60 BSC	
D2	1.05	1.15
E	1.60 BSC	
E2	0.45	0.55
e	0.50 BSC	
L	0.25	0.35
L2	0.17 REF	

GENERIC MARKING DIAGRAM*

*No marking due to clear package

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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